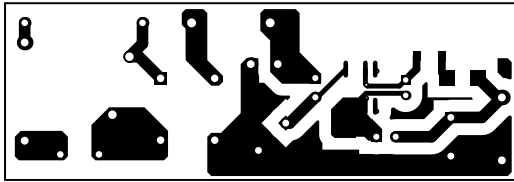
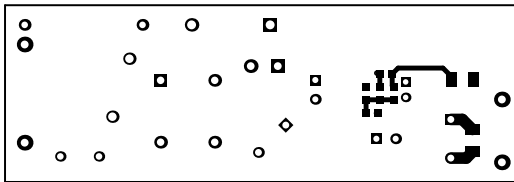


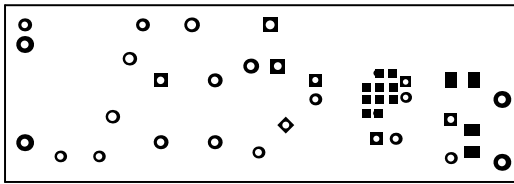
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9176 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | | | |
| PLOT NAME = Top Solder Mask | GENERATED : 6/26/2018 9:42:48 AM | TEXAS INSTRUMENTS | |



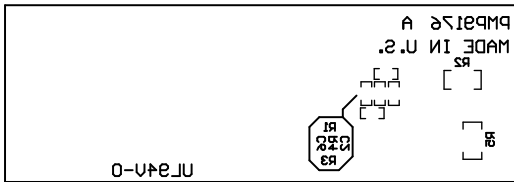
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9176 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer | | | |
| PLOT NAME = Top Layer | GENERATED : 6/26/2018 9:42:49 AM | TEXAS INSTRUMENTS | |



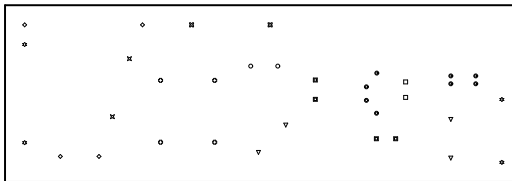
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9176 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | | | |
| PLOT NAME = Bottom Layer | GENERATED : 6/26/2018 9:42:50 AM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9176 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 6/26/2018 9:42:51 AM | TEXAS INSTRUMENTS | |

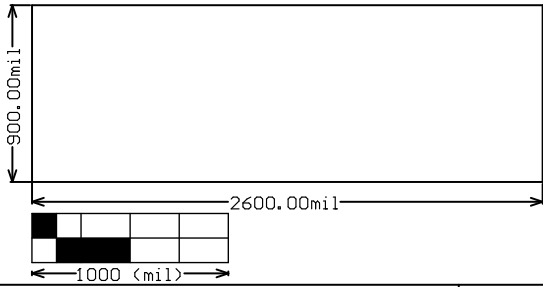


| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9176 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | | | |
| PLOT NAME = Bottom Overlay | GENERATED : 6/26/2018 9:42:52 AM | TEXAS INSTRUMENTS | |



| Symbol | Count | Hole Size | Plated | Hole Type |
|-----------------|-------|--------------------|--------|-----------|
| □ | 2 | 28.00mil (0.711mm) | PTH | Round |
| ○ | 2 | 39.37mil (1.000mm) | PTH | Round |
| ⊗ | 2 | 43.31mil (1.100mm) | PTH | Round |
| ⊗ | 2 | 45.28mil (1.150mm) | PTH | Round |
| ■ | 4 | 31.00mil (0.787mm) | PTH | Round |
| ◇ | 4 | 33.47mil (0.850mm) | PTH | Round |
| ▽ | 4 | 35.00mil (0.889mm) | PTH | Round |
| ⊙ | 4 | 38.00mil (0.965mm) | PTH | Round |
| ⊙ | 4 | 40.00mil (1.016mm) | PTH | Round |
| ⊙ | 8 | 10.00mil (0.254mm) | PTH | Round |
| 26 Total | | | | |

| | | | |
|----------------------------------|-----------------------|------------|---------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9176 | REV: A | SUN REV: Not In Version Control |
| LAYER NAME = Drill Drawing | | | |
| PLOT NAME = Drill Drawing | GENERATED : 6/26/2018 | 9:42:54 AM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP9176 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | | | |
| PLOT NAME = Board Dimensions | GENERATED : 6/26/2018 9:42:55 AM | TEXAS INSTRUMENTS | |

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